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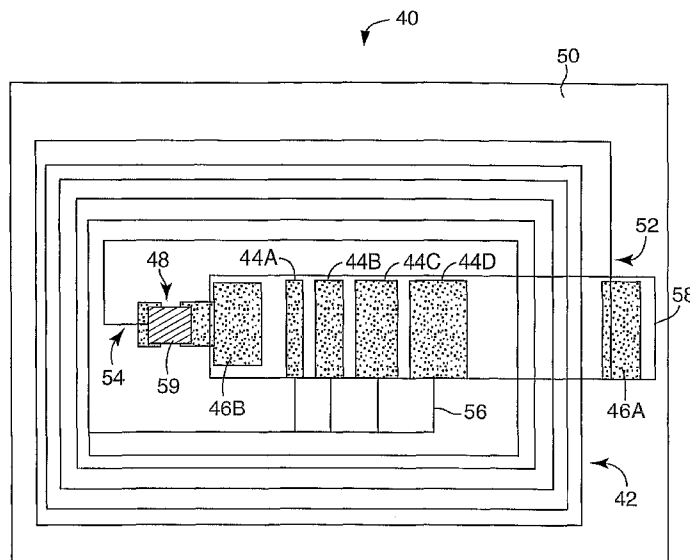
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(54) Title: FORMING ELECTROMAGNETIC COMMUNICATION CIRCUIT COMPONENTS USING DENSIFIED METAL POWDER



(57) Abstract: Manufacturing techniques are described for forming electrical components. For example, a layer of a metal powder composition is deposited onto at least a portion of a substrate. Pressure is applied to the metal powder composition by hydraulic press that has one or more projections in order to capture a pattern on the substrate. The metal powder composition compressed by the projections of the hydraulic press adhere to the substrate to form the captured pattern. The metal powder composition in regions not compressed by the projections of hydraulic press do not adhere to the substrate and may be removed. The metal powder composition may be compressed to form electrical components, such as antennae, capacitor plates, conduction pads and the like, for use in an electronic surveillance system (EAS), a radio frequency identification (RFID) system, or the like.

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